

PATENT  
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continuation-in-part of Application Serial No. 08/711,982, filed September 10, 1996, and issued August 4, 1998 as U.S. Patent No. 5,789,757, which claims priority from Application Serial No. 08/460,495, filed June 2, 1995, and issued March 7, 2000, as U.S. Patent No. 6,034,195, which is a continuation-in-part of Application Serial No. 08/300,721, filed September 2, 1994, and issued March 7, 2000 as U.S. Patent No. 6,034,194, each of which is hereby incorporated by reference in its entirety.

**In the Claims:**

Please cancel claims 28, 31, 34 and 45 without prejudice.

**Please amend claims 37, 40 and 43 as follows:**

37. (Amended) An assembly comprising a microelectronic device permanently adhered to a substrate by a cured aliquot of **[the] a die attach paste [according to claim 28] comprising:**

in the range of about 10 to 80 weight percent of a thermosetting resin composition, and  
in the range of about 20 to 90 weight percent of a conductive filler.

wherein said thermosetting resin composition comprises:

- a) a liquid maleimide,
- b) in the range of about 0.01 to about 10 equivalents of a vinyl compound per equivalent of maleimide,
- c) in the range of 0.2 to 3 weight percent of at least one free radical initiator, based on the total weight of the composition, and
- d) in the range of 0.1 to 10 weight percent of at least one coupling agent, based on the total weight of the composition, wherein said coupling agent has both a co-polymerizable function and a silicate ester function,